

C1808X229BHGACTU

Aliases (C1808X229BHGAC7800)

SMD Comm COG HV Flex, Ceramic, 2.2 pF, +/-0.1 pF, 3,000 VDC, COG, SMD, MLCC, FT-CAP, Ultra-Stable, 1808, 2.9 mm



Click [here](#) for the 3D model.

General Information

Series	SMD Comm COG HV Flex
Style	SMD Chip
Description	SMD, MLCC, FT-CAP, Ultra-Stable
Features	FT-CAP, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	81 mg
Shelf Life	78 Weeks
MSL	1

Specifications

Capacitance	2.2 pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	+/-0.1 pF
Voltage DC	3000 VDC
Dielectric Withstanding Voltage	3,600 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

Dimensions

Chip Size	1808
L	4.7mm +/-0.5mm
W	2mm +/-0.2mm
T	1.6mm +/-0.15mm
S	2.9mm MIN
B	0.7mm +/-0.35mm

Packaging Specifications

Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	1000

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